

What is Claimed is:

1. An LGA interconnect, for interconnection to further electrical components, said LGA interconnect comprising a substrate and a plurality of contact assemblies positioned and retained to said substrate for connection with said electrical components, and further comprising alignment members projecting from said substrate for aligning said substrate relative to at least one of the electrical components.

2. The LGA interconnect of claim 1, wherein each said contact assembly comprises a first contact extending from a first side of said substrate and a second contact extending from a second side of said substrate, said first and second contacts defining an array of contacts.

3. The LGA interconnect of claim 2, further comprising a frame housing surrounding said array of contacts.

4. The LGA interconnect of claim 3, wherein said alignment members are comprised of pins.

5. The LGA interconnect of claim 4, wherein said pins extend through said frame housing for registration directly to one of said electrical components.

6. The LGA interconnect of claim 5, wherein said pins are discrete members attached at diametrically opposite positions of said substrate.

7. The LGA interconnect of claim 5, wherein said frame housing can laterally float relative to said pins.

8. The LGA interconnect of claim 7, wherein said frame housing is comprised of first and second frame parts attached to each other.

9. The LGA interconnect of claim 8, wherein said first and second frame parts are attached at marginal edges of said substrate.

10. The LGA interconnect of claim 9, wherein one of said frame parts includes frame pins projecting through said substrate, while the other of said frame parts includes alignment apertures for receiving said frame pins in a press-fit manner.

11. The LGA interconnect of claim 9, wherein said frame housing further comprises at least one frame support member extending from side edges of said frame housing across said substrate, for supporting said electrical components above said substrate.

12. The LGA interconnect of claim 11, wherein said frame housing comprises frame support members having a cruciform configuration extending from opposite side edges of said frame housing and extending across said substrate, for supporting said electrical components above and below said substrate.

13. The LGA interconnect of claim 12, wherein said substrate is substantially rectangular in configuration and said frame support members define quadrants on both sides of said substrate.

14. An LGA interconnect, for interconnection to further electrical components, said LGA interconnect comprising:

a substrate having an upper surface and a lower surface, marginal side edges, and an array of contact receiving openings therein;

a plurality of contact assemblies positioned and retained in said substrate, with a first contact portion positioned above said upper surface and a second contact positioned below said lower surface, said plurality of contacts defining an array of contacts;

a frame housing positioned around a periphery of said substrate; and

alignment members projecting from said substrate for aligning said substrate relative to at least one of the electrical components.

15. The LGA interconnect of claim 14, wherein said alignment members are comprised of pins.

16. The LGA interconnect of claim 15, wherein said pins extend through said frame housing for registration directly to said electrical component.

17. The LGA interconnect of claim 16, wherein said pins are discrete members attached at diametrically opposite positions of said substrate.

18. The LGA interconnect of claim 16, wherein said frame housing can laterally float relative to said pins.

19. The LGA interconnect of claim 18, wherein said frame housing is comprised of first and second frame parts attached to each other.

20. The LGA interconnect of claim 19, wherein said first and second frame parts are attached at marginal edges of said substrate.

21. The LGA interconnect of claim 19, wherein one of said frame parts includes frame pins projecting through said substrate, while the other of said frame parts includes alignment apertures for receiving said frame pins.

22. The LGA interconnect of claim 19, wherein said frame housing further comprises at least one frame support member extending from side edges of said frame housing across said substrate, for supporting said electrical components above said substrate.

23. The LGA interconnect of claim 22, wherein said frame housing comprises frame support members having a cruciform configuration extending from opposite side edges of said frame housing and extending across said substrate, for supporting said electrical components above and below said substrate.

24. The LGA interconnect of claim 23, wherein said substrate is substantially rectangular in configuration and said frame support members define quadrants on both sides of said substrate.